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# INTERNATIONAL STANDARD



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**Semiconductor devices –  
Part 16-4: Microwave integrated circuits – Switches**

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## REDLINE VERSION



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### SEMICONDUCTOR DEVICES –

#### Part 16-4: Microwave integrated circuits – Switches

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**In this Redline version, a vertical line in the margin shows where the technical content is modified by amendments 1 and 2. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.**

International Standard IEC 60747-16-4 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

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## SEMICONDUCTOR DEVICES –

### Part 16-4: Microwave integrated circuits – Switches

#### 1 Scope

This part of IEC 60747 provides new measuring methods, terminology and letter symbols, as well as essential ratings and characteristics for integrated circuit microwave switches.

There are many combinations for RF ports in switches, such as SPST (single pole single throw), SPDT (single pole double throw), SP3T (single pole triple throw), DPDT (double pole double throw), etc. Switches in this standard are based on SPDT. However, this standard is applicable to the other types of switches.

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~~IEC 60617-13, Graphical symbols for diagrams – Part 13: Analogue elements~~

~~IEC 60747-1(1983), Semiconductor devices – Discrete devices and integrated circuits – Part 1: General  
Amendment 3 (1996)~~

IEC 60617, Graphical symbols for diagrams (available from <<http://std.iec.ch/iec60617>>)

IEC 60747-1:2006, Semiconductor devices – Part 1: General  
IEC 60747-1:2006/AMD1:2010

IEC 60747-4, Semiconductor devices – Discrete devices – Part 4: Microwave devices

IEC 60747-16-1:2001, Semiconductor devices – Part 16-1: Microwave integrated circuits – Amplifiers  
IEC 60747-16-1:2001/AMD1:2007  
IEC 60747-16-1:2001/AMD2:2017

IEC 60748-2, Semiconductor devices – Integrated circuits – Part 2: Digital integrated circuits

IEC 60748-3, Semiconductor devices – Integrated circuits – Part 3: Analogue integrated circuits

IEC 60748-4, Semiconductor devices – Integrated circuits – Part 4: Interface integrated circuits

IEC 61340-5-1:2007, Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements

IEC/TR 61340-5-2:2007, Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide

## FINAL VERSION

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Part 16-4: Microwave integrated circuits – Switches**



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